

ABSTRACT

**PROBE TIP TO DEVICE PAD ALIGNMENT IN OBSCURED VIEW PROBING
APPLICATIONS**

A method of performing alignment of an array of probe tips of a probe card to corresponding contact pads for wafer probing applications by performing the steps of: obtaining a backside image of the wafer; overlaying a mapping of the contact pads over the backside image; selecting contact pads as landing points; obtaining an image of the probe tips array; comparing the landing points to corresponding positions of probe tips; and, if the positions of probe tips are not aligned with the landing point, rotating the probe card to align the positions of probe tips to the landing points.

Figure 4